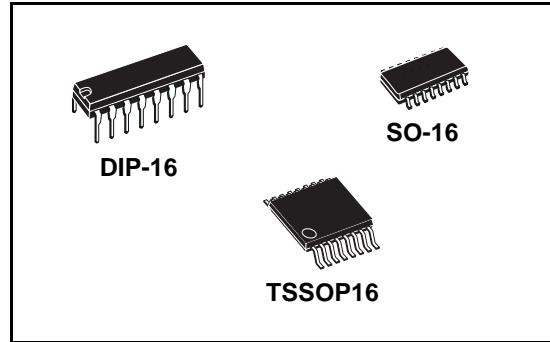


8-bit PISO shift register

Features

- High speed:
 - $t_{PD} = 15 \text{ ns}$ (typ.) at $V_{CC} = 6 \text{ V}$
- Low power dissipation:
 - $I_{CC} = 4 \mu\text{A}$ (max.) at $T_A = 25 \text{ }^\circ\text{C}$
- High noise immunity:
 $V_{NIH} = V_{NIL} = 28 \%$ V_{CC} (Min.)
- Symmetrical output impedance:
 $|I_{OH}| = I_{OL} = 4 \text{ mA}$ (min)
- Balanced propagation delays:
 $t_{PLH} \approx t_{PHL}$
- Wide operating voltage range:
 V_{CC} (opr) = 2 V to 6 V
- Pin and function compatible with
74 series 165



Description

The M74HC165 is a high speed CMOS 8-bit PISO (parallel-in-serial-out) shift register fabricated with silicon gate C²MOS technology. This device contains eight clocked master slave RS flip-flops connected as a shift register, with auxiliary gating to provide overriding asynchronous parallel entry. The parallel data enter when the shift/load input is low and can change while shift/load is low, provided that the recommended set-up and hold times are observed. For clocked operation, shift/load must be high. The two clock inputs perform identically: one can be used as a clock inhibit by applying a high signal, to allow this operation clocking is accomplished through a 2-input nor gate. To avoid double clocking, however, the inhibit signal should only go high while the clock is high. Otherwise the rising inhibit signal causes the same response as rising clock edge. All inputs are equipped with protection circuits against static discharge and transient excess voltage.

Table 1. Device summary

Order code	Package	Packaging
M74HC165B1R	DIP-16	Tube
M74HC165RM13TR	SO-16	Tape and reel
M74HC165TTR	TSSOP16	Tape and reel

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1 Logic symbols and I/O equivalent circuit

Figure 1. IEC logic symbols

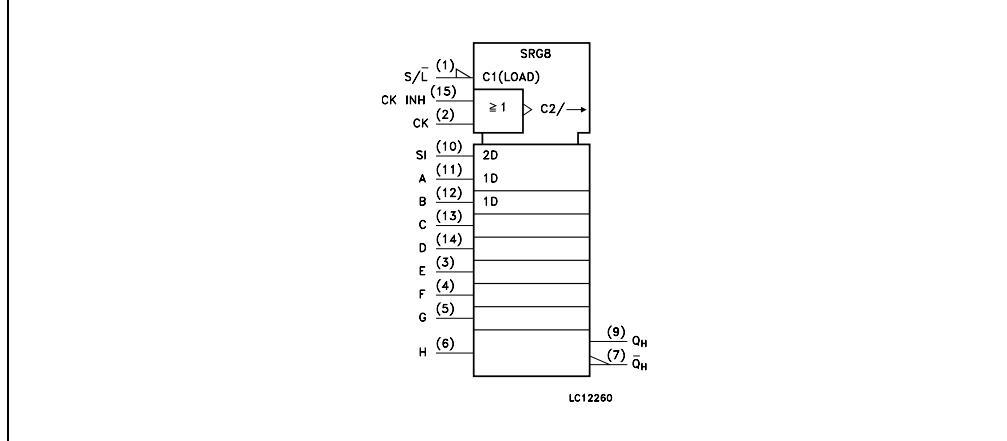
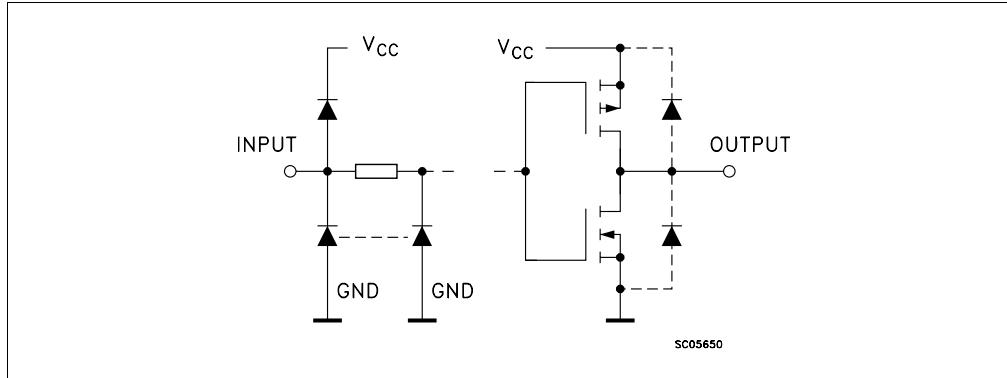


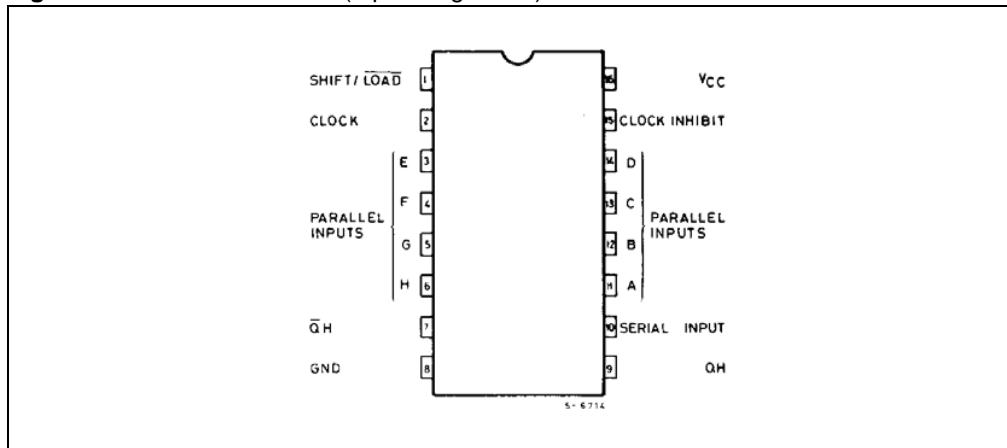
Figure 2. Input and output equivalent circuit



2 Pin settings

2.1 Pin connection

Figure 3. Pin connection (top through view)



2.2 Pin description

Table 2. Pin description

Pin number	Symbol	Name and function
1	SHIFT/LOAD	Data inputs
2	CLOCK	Clock input (low to high, edge triggered)
7	\overline{QH}	Complementary output
9	QH	Serial output
10	SI	Serial input
11, 12, 13, 14, 3, 4, 5, 6	A to H	Parallel data inputs
15	CLOCK INH	Clock inhibit
8	GND	Ground (0 V)
16	V _{CC}	Positive supply voltage

3 Logic states

3.1 Truth table

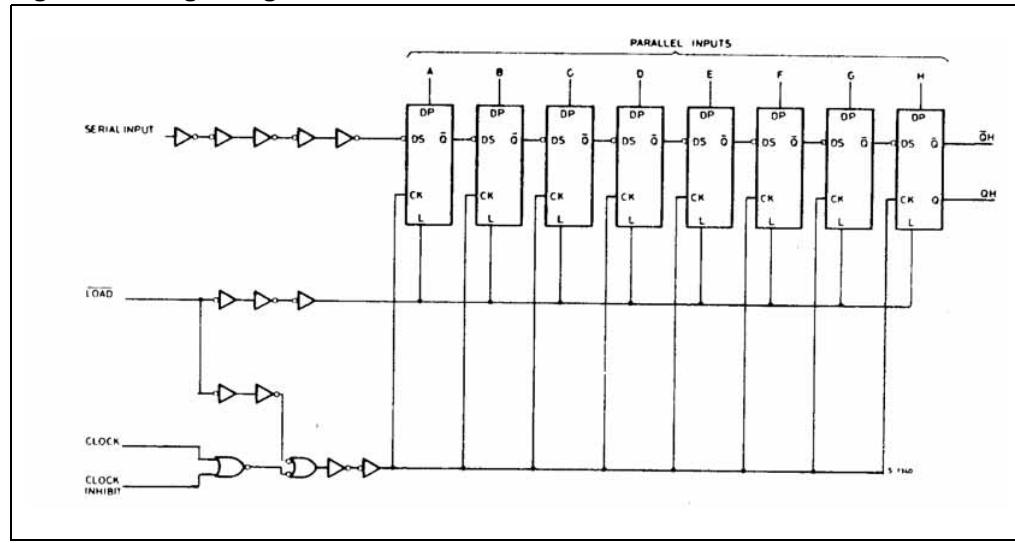
Table 3. Truth table

Inputs					Internal outputs		Outputs
Shift /Load	Clock INH	Clock	SI	A.....H	QA	QB	QH
L	X	X	X	a.....h	a	b	h
H	L	—	H	X	H	QAn	QGn
H	L	—	L	X	L	QAn	QGn
H	—	L	H	X	H	QAn	QGn
H	—	L	L	X	L	QAn	QGn
H	X	H	X	X	No change		
H	H	X	X	X	No change		

Note: *a.....h* : the level of steady input voltage at inputs *a* through *h* respectively *QAn - QGn* : the level of *QA - QG*, respectively. Before the most recent transition of the clock.

3.2 Logic diagram

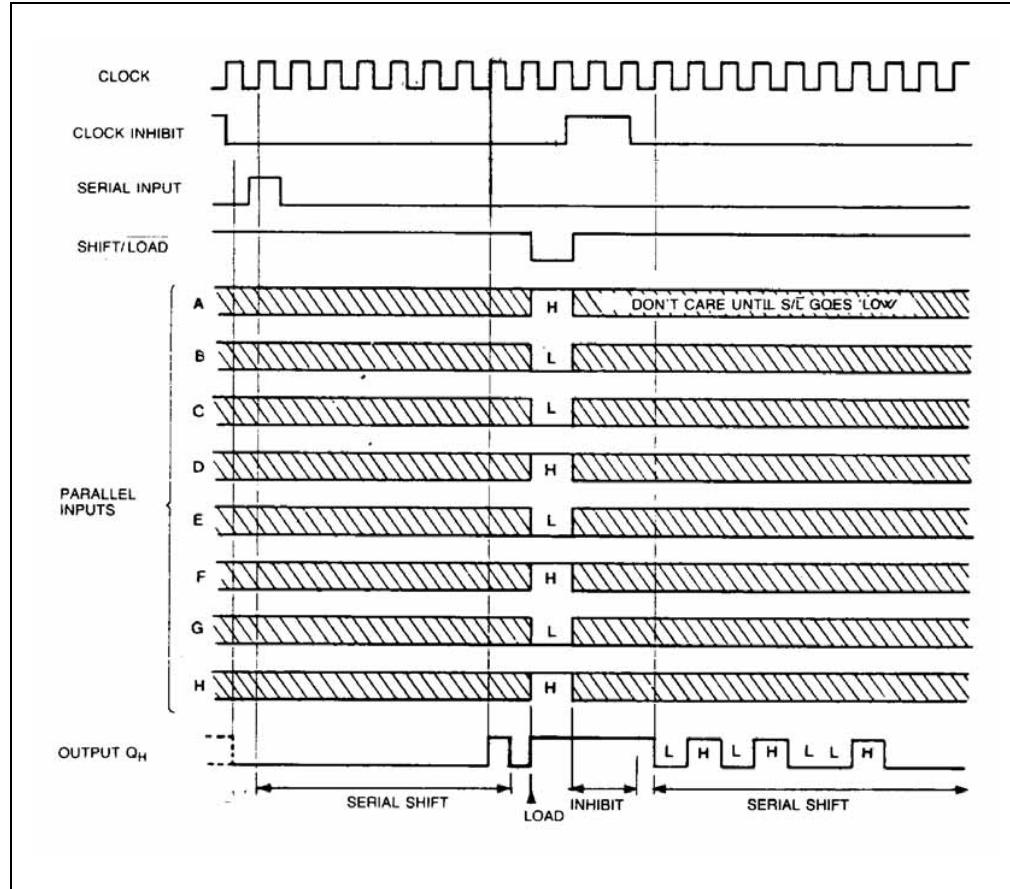
Figure 4. Logic diagram



Note: This logic diagram has not to be used to estimate propagation delays

3.3 Timing chart

Figure 5. Timing chart



4 Maximum rating

Stressing the device above the rating listed in the “absolute maximum ratings” table may cause permanent damage to the device. These are stress ratings only and operation of the device at these or any other conditions above those indicated in the operating sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability. Refer also to the STMicroelectronics sure program and other relevant quality documents.

Table 4. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{CC}	Supply voltage	-0.5 to +7	V
V_I	DC input voltage	-0.5 to $V_{CC} + 0.5$	V
V_O	DC output voltage	-0.5 to $V_{CC} + 0.5$	V
I_{IK}	DC input diode current	± 20	mA
I_{OK}	DC output diode current	± 20	mA
I_O	DC output current	± 25	mA
I_{CC} or I_{GND}	DC V_{CC} or ground current	± 50	mA
P_D	Power dissipation	500 ⁽¹⁾	mW
T_{stg}	Storage temperature	-65 to +150	°C
T_L	Lead temperature (10 sec)	300	°C

1. (*) 500 mW at 65 °C; derate to 300 mW by 10 mW/°C from 65°C to 85°C

4.1 Recommended operating conditions

Table 5. Recommended operating conditions

Symbsol	Parameter	Value	Unit
V_{CC}	Supply voltage	2 to 6	V
V_I	Input voltage	0 to V_{CC}	V
V_O	Output voltage	0 to V_{CC}	V
T_{op}	Operating temperature	-55 to 125	°C
t_r, t_f	Input rise and fall time	$V_{CC} = 2.0$ V	0 to 1000
		$V_{CC} = 4.5$ V	0 to 500
		$V_{CC} = 6.0$ V	0 to 400

5 Electrical characteristics

Table 6. DC specifications

Symbol	Parameter	Test condition		Value						Unit	
		V_{CC} (V)		$T_A = 25^\circ C$			$-40 \text{ to } 85^\circ C$		$-55 \text{ to } 125^\circ C$		
				Min	Typ	Max	Min	Max	Min	Max	
V_{IH}	High level input voltage	2.0		1.5			1.5		1.5		V
		4.5		3.15			3.15		3.15		
		6.0		4.2			4.2		4.2		
V_{IL}	Low level input voltage	2.0				0.5		0.5		0.5	V
		4.5				1.35		1.35		1.35	
		6.0				1.8		1.8		1.8	
V_{OH}	High level output voltage	2.0	$I_O = -20 \mu A$	1.9	2.0		1.9		1.9		V
		4.5	$I_O = -20 \mu A$	4.4	4.5		4.4		4.4		
		6.0	$I_O = -20 \mu A$	5.9	6.0		5.9		5.9		
		4.5	$I_O = -4.0 mA$	4.18	4.31		4.13		4.10		
		6.0	$I_O = -5.2 mA$	5.68	5.8		5.63		5.60		
V_{OL}	Low level output voltage	2.0	$I_O = 20 \mu A$		0.0	0.1		0.1		0.1	V
		4.5	$I_O = 20 \mu A$		0.0	0.1		0.1		0.1	
		6.0	$I_O = 20 \mu A$		0.0	0.1		0.1		0.1	
		4.5	$I_O = 4.0 mA$		0.17	0.26		0.33		0.40	
		6.0	$I_O = 5.2 mA$		0.18	0.26		0.33		0.40	
I_I	Input leakage current	6.0	$V_I = V_{CC} \text{ or GND}$			± 0.1		± 1		± 1	μA
I_{CC}	Quiescent supply current	6.0	$V_I = V_{CC} \text{ or GND}$			4		40		80	μA

Table 7. AC electrical characteristics ($C_L = 50 \text{ pF}$, Input $t_r = t_f = 6\text{ns}$)

Symbol	Parameter	Test condition		Value						Unit	
		V_{CC} (V)		$T_A = 25^\circ\text{C}$			$-40 \text{ to } 85^\circ\text{C}$		$-55 \text{ to } 125^\circ\text{C}$		
				Min	Typ	Max	Min	Max	Min	Max	
$t_{TLH} t_{THL}$	Output transition time	2.0			30	75		95		110	ns
		4.5			8	15		19		22	
		6.0			7	13		16		19	
$t_{PLH} t_{PHL}$	Propagation delay time (CLOCK - QH, $\bar{Q}H$)	2.0			55	150		190		225	ns
		4.5			18	30		38		45	
		6.0			15	26		33		38	
$t_{PLH} t_{PHL}$	Propagation delay time (SHIFT/LOAD - QH, $\bar{Q}H$)	2.0			65	165		205	250		ns
		4.5			21	33		41		50	
		6.0			18	28		35		43	
$t_{PLH} t_{PHL}$	Propagation delay time (H - QH, $\bar{Q}H$)	2.0			52	135		170		205	ns
		4.5			17	27		34		41	
		6.0			14	23		29		35	
f_{MAX}	Maximum clock frequency	2.0		7.4	15		6.0		4.8		MHz
		4.5		37	60		30		24		
		6.0		44	71		35		28		
$t_{W(H)}$ $t_{W(L)}$	Minimum pulse width (CLOCK)	2.0			24	75		95		110	ns
		4.5			6	15		19		22	
		6.0			5	13		16		19	
$t_{W(L)}$	Minimum pulse width (SHIFT/LOAD)	2.0			32	75		95		110	ns
		4.5			8	15		19		22	
		6.0			7	13		16		19	
t_s	Minimum set-up time (PI-SHIFT/LOAD) (SI - CLOCK) (SHIFT/LOAD - CK)	2.0			24	75		95		110	ns
		4.5			6	15		19		22	
		6.0			5	13		16		19	
t_h	Minimum hold time (PI - SHIFT/LOAD) (SI - CLOCK) (SHIFT/LOAD - CK)	2.0				0		0		0	ns
		4.5				0		0		0	
		6.0				0		0		0	
t_{REM}	Minimum removal time (CLOCK - CK INH)	2.0			20	75		95		110	ns
		4.5			5	15		19		22	
		6.0			4	13		16		19	

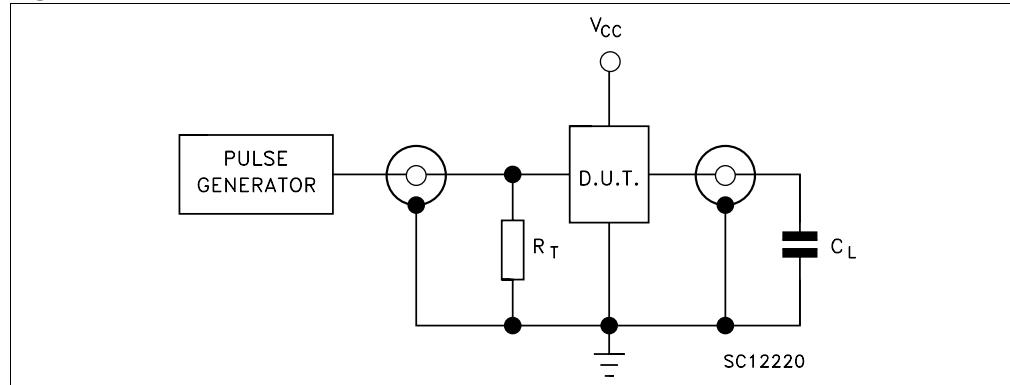
Table 8. Capacitive characteristics

Symbol	Parameter	Test condition		Value						Unit	
		V _{CC} (V)		T _A = 25 °C			-40 to 85 °C		-55 to 125 °C		
				Min	Typ	Max	Min	Max	Min	Max	
C _{IN}	Input capacitance	5.0			5	10		10		10	pF
C _{PD}	Power dissipation capacitance ⁽¹⁾	5.0			55						pF

1. C_{PD} is defined as the value of the IC's internal equivalent capacitance which is calculated from the operating current consumption without load. (Refer to Test Circuit). Average operating current can be obtained by the following equation.
 $I_{CC(opr)} = C_{PD} \times V_{CC} \times f_{IN} + I_{CC}$

6 Test circuit

Figure 6. Test circuit



$C_L = 50 \text{ pF}$ or equivalent (includes jig and probe capacitance)

$R_T = Z_{OUT}$ of pulse generator (typically 50Ω)

7 Waveforms

Figure 7. Serial mode propagation delay ($f = 1$ MHz; 50% duty cycle)

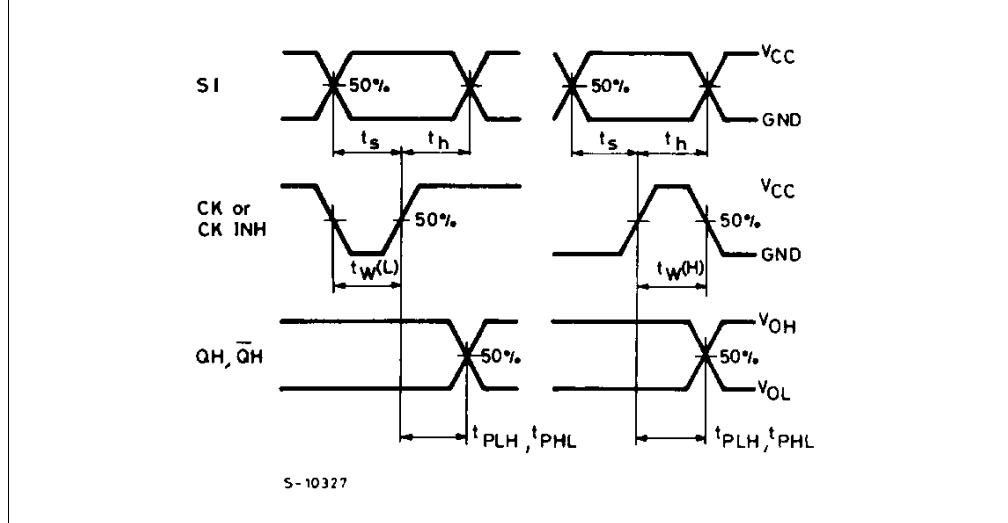


Figure 8. Parallel mode propagation delay ($f = 1$ MHz; 50% duty cycle)

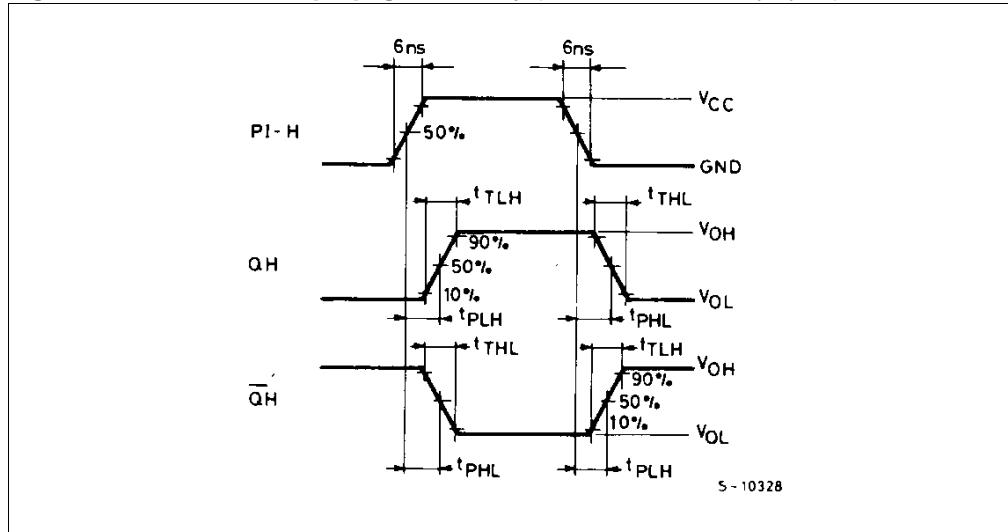


Figure 9. Minimum pulse width (S/\bar{L}), propagation delay times
($f = 1$ MHz; 50% duty cycle)

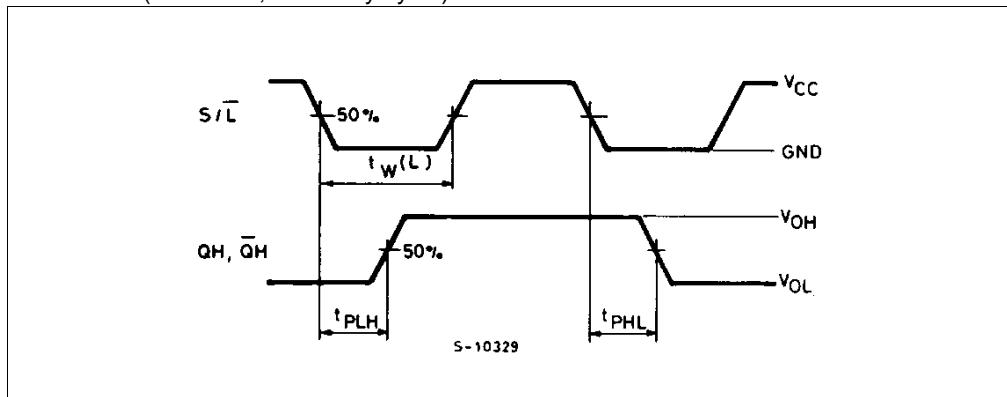


Figure 10. Setup and hold time (PI to S/\bar{L}) ($f = 1$ MHz; 50% duty cycle)

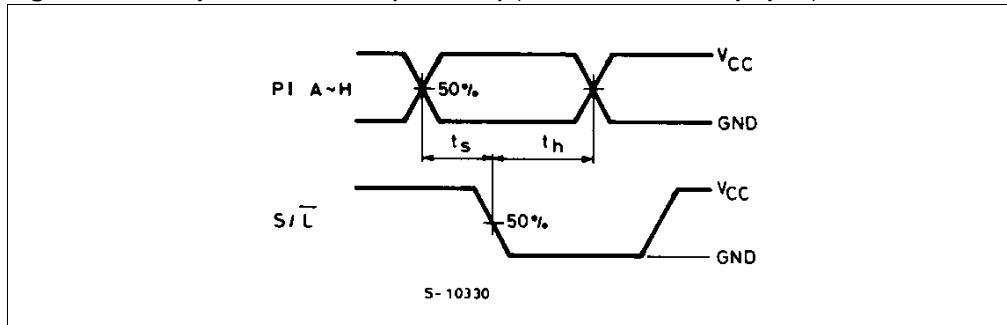
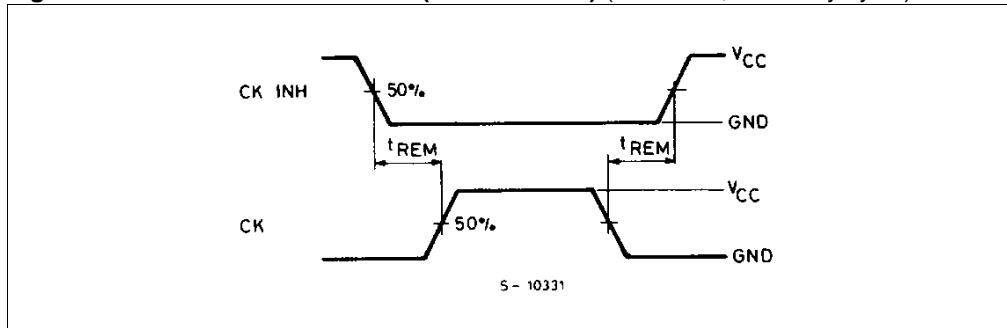


Figure 11. Minimum removal time (CK INH to CK) ($f = 1$ MHz; 50% duty cycle)

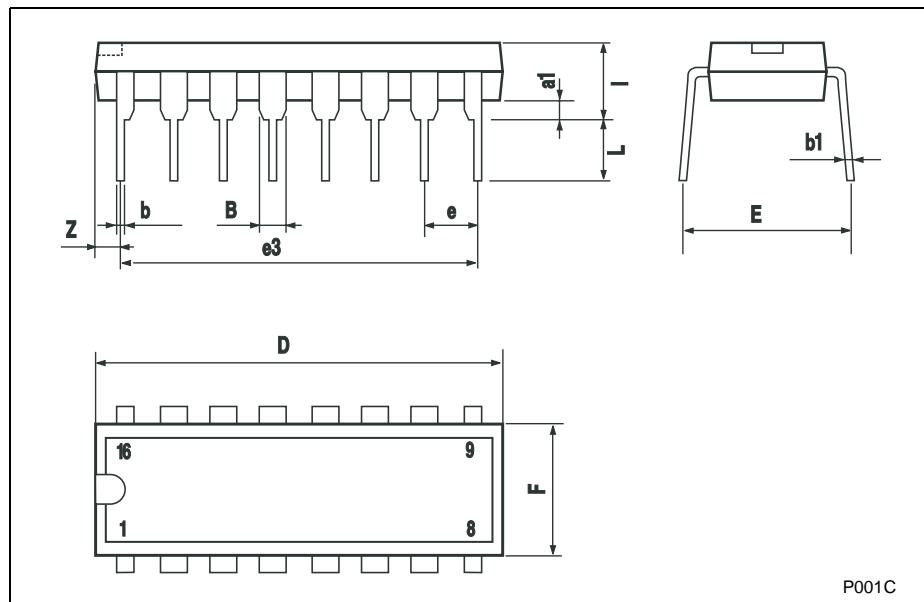


8 Package mechanical data

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a Lead-free second level interconnect . The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com.

Plastic DIP-16 (0.25) MECHANICAL DATA

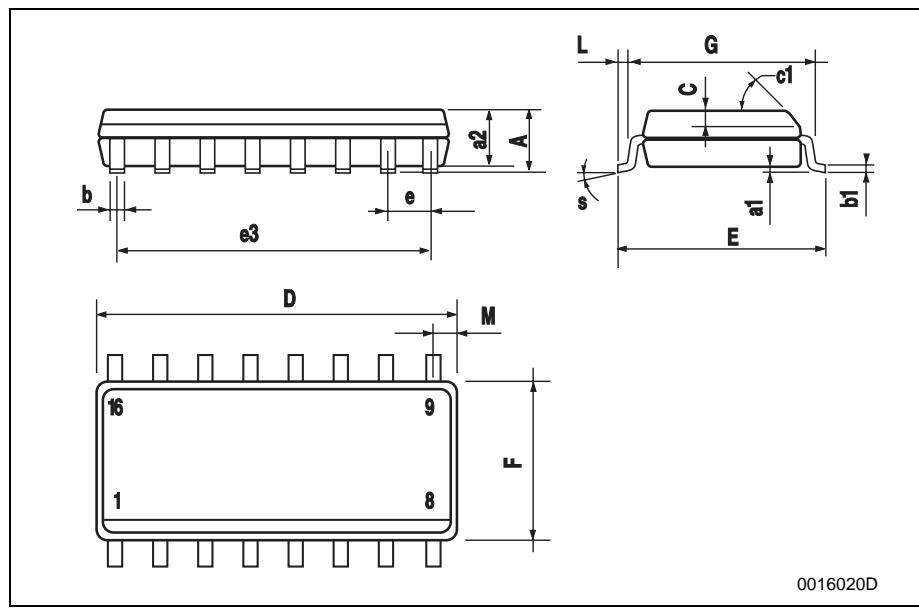
DIM.	mm.			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
a1	0.51			0.020		
B	0.77		1.65	0.030		0.065
b		0.5			0.020	
b1		0.25			0.010	
D			20			0.787
E		8.5			0.335	
e		2.54			0.100	
e3		17.78			0.700	
F			7.1			0.280
I			5.1			0.201
L		3.3			0.130	
Z			1.27			0.050



P001C

SO-16 MECHANICAL DATA

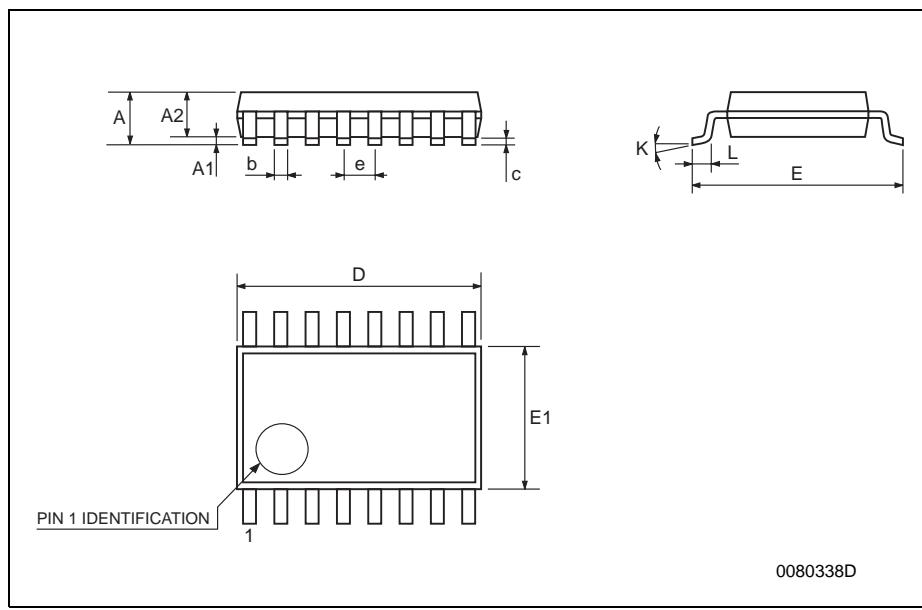
DIM.	mm.			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A			1.75			0.068
a1	0.1		0.25	0.004		0.010
a2			1.64			0.063
b	0.35		0.46	0.013		0.018
b1	0.19		0.25	0.007		0.010
C		0.5			0.019	
c1			45° (typ.)			
D	9.8		10	0.385		0.393
E	5.8		6.2	0.228		0.244
e		1.27			0.050	
e3		8.89			0.350	
F	3.8		4.0	0.149		0.157
G	4.6		5.3	0.181		0.208
L	0.5		1.27	0.019		0.050
M			0.62			0.024
S			8° (max.)			



0016020D

TSSOP16 MECHANICAL DATA

DIM.	mm.			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A			1.2			0.047
A1	0.05		0.15	0.002	0.004	0.006
A2	0.8	1	1.05	0.031	0.039	0.041
b	0.19		0.30	0.007		0.012
c	0.09		0.20	0.004		0.0079
D	4.9	5	5.1	0.193	0.197	0.201
E	6.2	6.4	6.6	0.244	0.252	0.260
E1	4.3	4.4	4.48	0.169	0.173	0.176
e		0.65 BSC			0.0256 BSC	
K	0°		8°	0°		8°
L	0.45	0.60	0.75	0.018	0.024	0.030



Tape & Reel SO-16 MECHANICAL DATA						
DIM.	mm.			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A			330			12.992
C	12.8		13.2	0.504		0.519
D	20.2			0.795		
N	60			2.362		
T			22.4			0.882
Ao	6.45		6.65	0.254		0.262
Bo	10.3		10.5	0.406		0.414
Ko	2.1		2.3	0.082		0.090
Po	3.9		4.1	0.153		0.161
P	7.9		8.1	0.311		0.319

The drawing consists of three views of the SO-16 package. The top view shows a circle with diameter A and a smaller concentric circle with diameter D. The side view shows height C and height T. The bottom view shows the chip carrier with pins, indicating bond pad locations and lead spacing Po. Dimensions Bo and Ko are also shown. A note at the bottom right states: "Note: Drawing not in scale".

Tape & Reel SSOP16 MECHANICAL DATA						
DIM.	mm.			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A			330			12.992
C	12.8		13.2	0.504		0.519
D	20.2			0.795		
N	60			2.362		
T			22.4			0.882
Ao	8.4		8.6	0.331		0.339
Bo	6.7		6.9	0.264		0.272
Ko	2.9		3.1	0.114		0.122
Po	3.9		4.1	0.153		0.161
P	11.9		12.1	0.468		0.476

The drawing shows the physical dimensions of the SSOP16 package. The top view illustrates the total width A, the center hole diameter D, and the lead spacing Bo. The side view shows the total height C, the lead thickness T, and the lead pitch N. The bottom view provides a detailed look at the lead configuration, including the lead width Ao and the lead pitch Po.

Note: Drawing not in scale

9 Revision history

Table 9. Document revision history

Date	Revision	Changes
9-Jul-2001	3	Final release.
21-Mar-2007	4	The document has been reformatted, updated Table 2: Pin description on page 4
26-May-2008	5	Removed: M74HC165M1R order code. Minor changes in the text. Added: SO-16 and TSSOP16 tape and reel specifications.

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